



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-08-06
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BD139-10	TCOT*B715S6C	A	Z6TA	2015-08-06
Amount		UoM	Unit type	ST ECOPACK Grade
640.00		mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.8 - 7.8 - 2.7	3	Through-hole	
Comment	Package: SOT-32			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TCOT#B71556C					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	0.829	mg	supplier	die	Silicon (Si)	7440-21-3		0.801	mg	966184	1250
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	10870	14
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	13285	17
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	1208	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	2415	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	6039	8
Leadframe	Copper & its alloys	358.989	mg	supplier	alloy	Copper (Cu)	7440-50-8		283.601	mg	789999	443127
				supplier	alloy	Iron (Fe)	7439-89-6		53.849	mg	150002	84139
				supplier	alloy	Phosphorous (P)	12185-10-3		14.359	mg	39998	22436
				supplier	metallization	Nickel (Ni)	7440-02-0		7.180	mg	20001	11219
Soft solder	Solder	3.890	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.730	mg	958869	5828
				supplier	solder	Tin (Sn)	7440-31-5		0.070	mg	17995	109
				supplier	solder	Silver (Au)	7440-22-4		0.090	mg	23136	141
Bonding wires	Other inorganic materials	0.401	mg	supplier	wire	Copper (Cu)	7440-50-8		0.401	mg	1000000	627
Encapsulation	Other inorganic materials	272.752	mg	supplier	mold compound	Silica (SiO2)	60676-86-0		256.386	mg	939997	400603
				supplier	mold compound	Antimony Oxide	1309-64-4		13.638	mg	50001	21309
				supplier	mold compound	Carbon Black	1333-86-4		2.728	mg	10002	4263
Connections coating	Solder	3.139	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.139	mg	1000000	4905